

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2014/03/05	Jamie Zie

NOTES:

1.MATERIAL:

- 1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC.
- 1.2 SPRING CONTACT: COPPER ALLOY.
- 1.3 FLAT CONTACT;COPPER ALLOY
- 1.4 SHELL :STAINLESS STEEL.

2.FINISH:

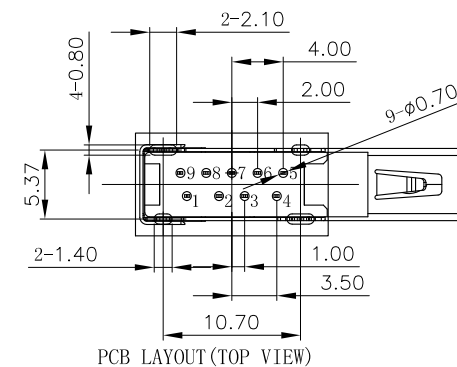
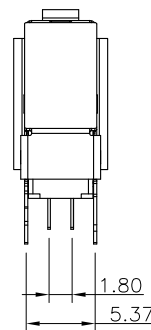
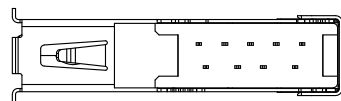
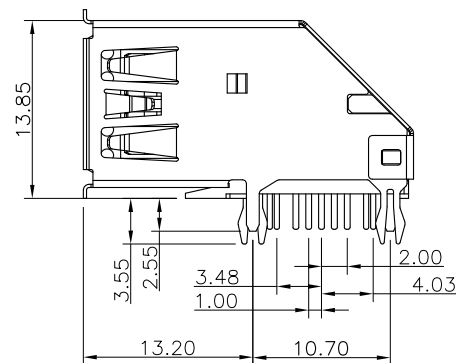
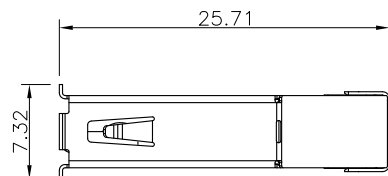
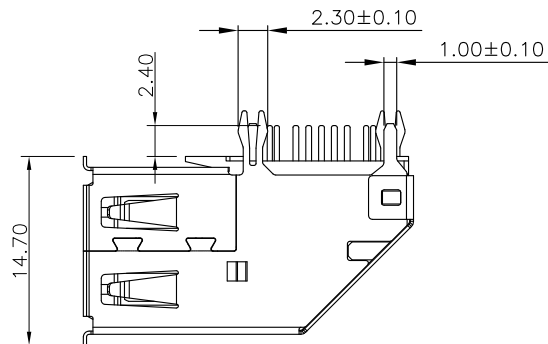
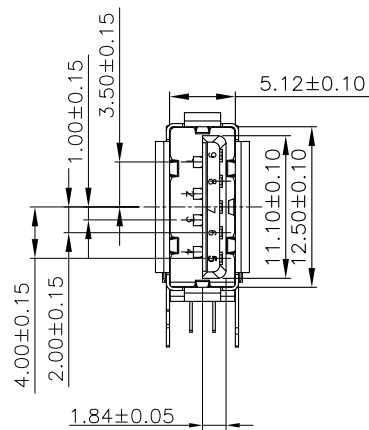
- 2.1 CONTACT: GOLD PLATING ON CONTACT AREA,MATTE TIN PLATING ON SOLDER TAIL AREA,NICKEL UNDER PLATING.
- 2.2 SHELL: SOLDERABILITY NICKEL PLATING OVER ALL.

MATRIX PART NO:

MUSB - 09 - 15 - 48

MATRIX USB Pin Number Planting
01:Gold Flash
15:15u"
30:30u"

Series number



NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X:X X:XX ±0.38 X:XXX ±0.25 X:XXX ±0.13 ANGLE: ±3°		DESIGN BY : Jamie Zie	DATE : 2014/03/05	PART NAME: 側插 USB 3.0 DIP CONN
CHECKED BY: Vicky Hsieh		DATE : 2014/03/05	PART NO.	MUSB09-15-48
APPROVED BY1: Richard Hsieh		DATE : 2014/03/05	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2014/03/05	DRAW NO.	
SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 1